

INFORMATION DISCLOSURE CITATION <i>(Use several sheets if necessary)</i>				Docket Number (Optional) FIS92000034-1		Application Number 5791	
				Applicant(s) DR. SUDIPTA K. RAY ET AL			
				Filing Date 01/12/93		Group Art Unit JC872 U.S. 5791	
<b>U.S. PATENT DOCUMENTS</b>							
*EXAMINER INITIAL	REF	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
1m		4,945,400	07/31/90				
1m		5,179,609	01/12/93				
1m		5,257,336	10/26/93				
1m		5,259,054	11/2/93				
1m		5,937,124	08/10/99				
<b>FOREIGN PATENT DOCUMENTS</b>							
REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation	
1m						YES	NO
1m							
1m							
1m							
1m							
<b>OTHER DOCUMENTS</b> <i>(Including Author, Title, Date, Pertinent Pages, Etc.)</i>							
1m		IEEE 1997 ; W. Pittroff, J. Barnikow, A. Klein, P. Kurpas, U. Merkel, K. Vogel & J. Wurfl, Electronic Components and Technology Conference "Flip Chip Mounting of Laser Diodes with Au/Sn Solder Bumps; Bumping, Self-Alignment and Laser Behavior", Pages 1235-1241					
1m							
EXAMINER				DATE CONSIDERED			
1m				7-16-3			

EXAMINEE

**EXAMINER:** Initial if not considered. Include

POSA/REV/04

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